# Advance Information

# **Low Capacitance Quad Array for ESD Protection**

This integrated transient voltage suppressor device (TVS) is designed for applications requiring transient overvoltage protection. It is intended for use in sensitive equipment such as computers, printers, business machines, communication systems, medical equipment, and other applications. Its integrated design provides very effective and reliable protection for four separate lines using only one package. These devices are ideal for situations where board space is at a premium.

#### **Features**

- ESD Protection: IEC61000-4-2: Level 4 MILSTD 883C - Method 3015-6: Class 3
- Four Separate Unidirectional Configurations for Protection
- Low Leakage Current < 1 µA @ 3 V
- Power Dissipation: 380 mW
- Small SOT-553 SMT Package
- Low Capacitance (8 pF Typical @ 3 V)

#### **Benefits**

- Provides Protection for ESD Industry Standards: IEC 61000, HBM
- Protects the Line Against Transient Voltage Conditions in Either Direction
- Minimize Power Consumption of the System WWW.DZSC.COM
- Minimize PCB Board Space

#### Typical Applications

- Instrumentation Equipment
- Serial and Parallel Ports
- Microprocessor Based Equipment
- Notebooks, Desktops, Servers
- Cellular and Portable Equipment

This document contains information on a new product. Specifications and information herein are subject to change without notice. WWW.DZSC.COM



# ON Semiconductor®

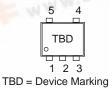
#### http://onsemi.com





CASE 463A **PLASTIC** 

## MARKING DIAGRAM



#### ORDERING INFORMATION

Device	Package	Shipping	
NZQA5V6AXV5T1	SOT-553	4000/Tape & Reel	



# **MAXIMUM RATINGS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Power Dissipation 8 X 20 μs Double Exponential Waveform (Note 1)	P <sub>PK</sub>	20	W
Thermal Resistance – Junction to Ambient Above 25°C, Derate	$R_{ heta JA}$	327 3.05	°C/W mW/°C
Operating Junction Temperature Range	T <sub>J</sub>	-40 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-55 to +150	°C
Lead Solder Temperature – Maximum 10 Seconds Duration	T <sub>L</sub>	260	°C

# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

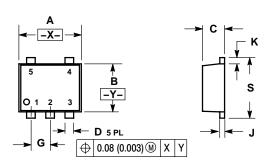
Characteristic	Symbol	Min	Тур	Max	Unit
Breakdown Voltage (I <sub>T</sub> = 1 mA) (Note 3)		5.3	5.6	5.9	V
Leakage Current (V <sub>RWM</sub> = 3.0 V)		-	-	1.0	μΑ
Clamping Voltage 1 (I <sub>PP</sub> = 1.6 A, 8 X 20 μs Waveform)	V <sub>C</sub>	-	10	TBD	V
Maximum Peak Pulse Current (8 X 20 μs Waveform)	I <sub>PP</sub>	-	1.6	TBD	Α
Junction Capacitance – (V <sub>R</sub> = 0 V, f = 1 MHz) – (V <sub>R</sub> = 3 V, f = 1 MHz)	CJ	- -	15 8.0	TBD TBD	pF

<sup>3.</sup> V<sub>BR</sub> is measured at pulse test current I<sub>T</sub>.

Non-repetitive current pulse per Figure TBD.
 Only 1 diode under power. For all 4 diodes under power, P<sub>D</sub> will be 25%. Mounted on FR4 board with min. pad.

## **PACKAGE DIMENSIONS**

SOT-553, 5-LEAD CASE 463B-01 ISSUE O



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETERS
  3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	1.50	1.70	0.059	0.067	
В	1.10	1.30	0.043	0.051	
С	0.50	0.60	0.020	0.024	
D	0.17	0.27	0.007	0.011	
G	0.50 BSC		0.020 BSC		
J	0.08	0.18	0.003	0.007	
K	0.10	0.30	0.004	0.012	
S	1.50	1.70	0.059	0.067	

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